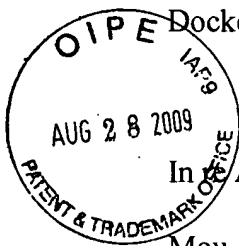


08-31-09

FW



Docket No.: 085027-0058

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Application of

Mou-Shiung Lin, et al.

Application No.: 10/055,560

Filed: January 22, 2002

For: INTEGRATED CHIP PACKAGE STRUCTURE USING METAL SUBSTRATE AND
METHOD OF MANUFACTURING THE SAME

: Customer Number: 89518
:
: Confirmation Number: 6103
:
: Group Art Unit: 2813
:
: Examiner: MITCHELL, JAMES M.

TRANSMITTAL OF POWER OF ATTORNEY


Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Transmitted herewith is a Power Of Attorney to Prosecute Applications Before the USPTO, together with a Statement Under 37 CFR 3.73(b), which revokes all previous powers of attorney given in the above-identified application and associates the application with Customer Number 89518.

Respectfully submitted,

McDERMOTT WILL & EMERY LLP


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Date: August 28, 2009

**Please recognize our Customer No. 89518
as our correspondence address.**